



Final Product/Process Change Notification

Document #:FPCN25336XA

Issue Date:14 Dec 2023

Title of Change:	Qualification Assembly site in UTAC Thailand for FSA3157L6X and NC7SZ66L6X
Proposed First Ship date:	21 Mar 2024 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office or mitch.paris@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local onsemi Sales Office or Lalan.Ortega@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	The affected products will be identified with date code
Change Category:	Assembly Change
Change Sub-Category(s):	Material Change, Manufacturing Site Transfer

Sites Affected:

onsemi Sites	External Foundry/Subcon Sites
None	UTAC, Thailand

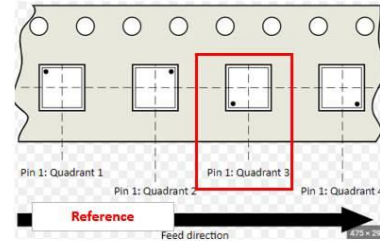
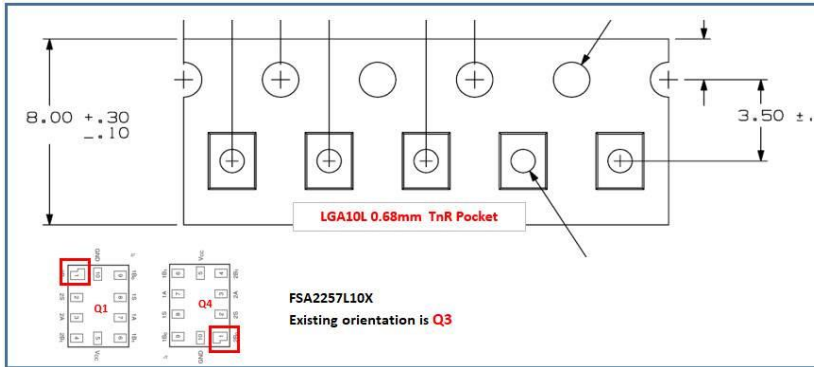
Description and Purpose:

onsemi is announcing the qualification of new assembly site UTAC Thailand which includes new die attach, mold compound, package substrate and Carrier tape for FSA3157L6X and NC7SZ66L6X.

Product material change description:

	From	To
Assembly Site	HANA Thailand	UTAC Thailand
Die Attach	DA FILM LI LE5003 P8AS 100ST	DAF HR5104
Mold Compound	MC NITTO GE100LFCG 14MMX4.6G	Kyosera / KE-G1250LKDS-30 BU10C
Package Substrate	PS LGAB LOGIC KINSUS	FAST PRINT LGA SUBSTRATE
Carrier tape	Carrier tape for package thickness at 0.55 max	Carrier tape for package thickness at 0.68 max
MPQ/ PCQ	5,000 pcs	3,000 pcs
Packing PIN 1 orientation	Q3	Q1

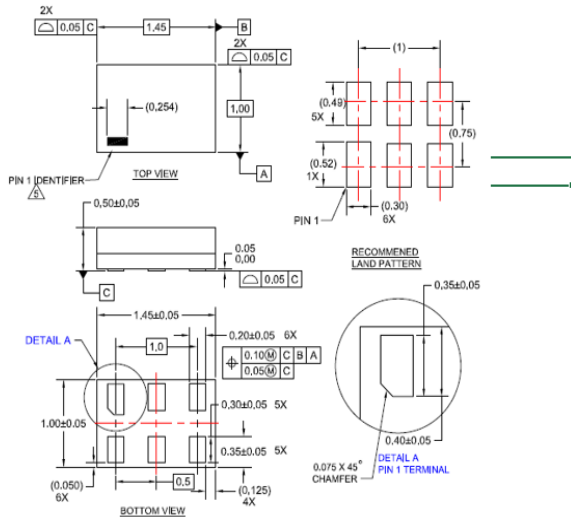
- Packing PIN 1 orientation in TnR will change from Q3 to Q1



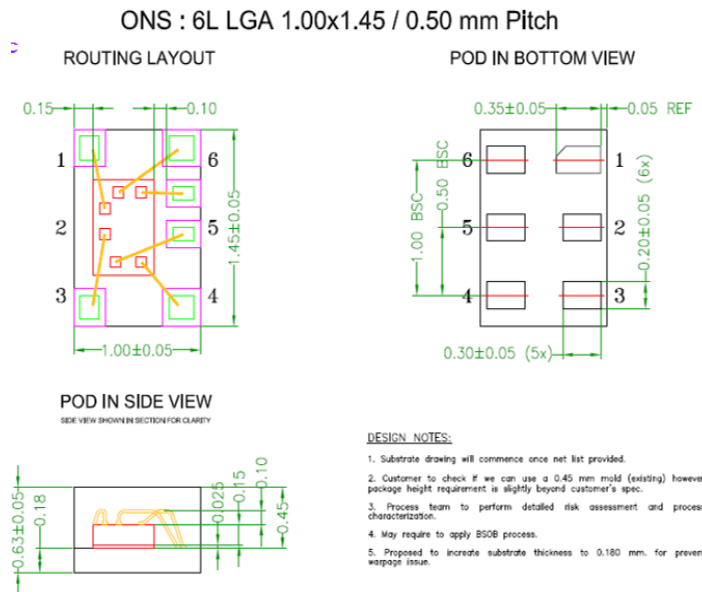
- For FSA3157L6X, NC7SZ66L6X

Dimension	HANA Thailand (existing)			UTAC Thailand (new site)			Remark
	Min	Nom	Max	Min	Nom	Max	
A	0.45	0.50	0.55	0.58	0.63	0.68	UTAC thicker than HANA
L	0.25	0.30	0.35	0.20	0.25	0.30	Outer lead smaller than existing but still can use the same footprint.
L1	0.30	0.35	0.40	0.25	0.30	0.35	Outer lead smaller than existing but still can use the same footprint.
K	-	0.05	-	-	0.10	-	Still can use the same footprint.

HANA Thailand



UTAC Thailand



There is no product marking change for this type of change.



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Reliability Data Summary:

QV DEVICE NAME: **FSA3157L6X**

RMS: **S86640, S89551, O91426**

PACKAGE: **SIP 6L LGA 1.45x1.00 mm**

Test	Specification	Condition	Interval	Test Result
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs	0 / 231
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs	0 / 231
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C		0 / 693
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cyc	0 / 231
Highly Accelerated Stress Test	JESD22 A110	TA= +130°C, RH = 85%, PSIG= 18.8, bias	96 hrs	0 / 231
Unbiased Highly Accelerated Stress Test	JESD22-A118	T= +130°C, RH=85%, p = 18.8 psig unbiased	96 hrs	0 / 231
Solderability	JSTD002	Ta = 245°C, 5 sec		0 / 45
Physical Dimensions	JESD22-B120			0 / 30

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
NC7SZ66L6X	FSA3157L6X
FSA3157L6X	FSA3157L6X